# AIP1640 LED Control Dedicated Circuit Product Introduction

#### 1. Overview

It is a dedicated circuit for LED driving control (LED Display) with integrated MCU digital ports, data latch, LED high voltage driver and other circuits. This product has excellent performance and reliable quality. It is mainly applied to display drive of small household appliances and electronic scales.

#### Features:

- CMOS process
- Brightness adjustment circuit (duty cycle 8 levels adjustable)
- Two-wire serial interface (CLK, DIN)
- Oscillation mode: Built-in RC oscillation (450KHz+5%)
- Built-in power-on reset circuit
- Built-in automatic blanking circuit
- Display mode (8 segments × 16 bits), support common cathode digital tube output
- Package: SOP28

# 2. Functional Diagram and Pin Description

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Pin Diagram 2 GRID13 GRID10	] 27
3 GRID14 GRID9	26
4 GRID15 GRID8	] 25
5 GRID16 GRID7	] 24
6 VSS GRID6	23
7 DIN GRID5	22
8 SCLK GRID4	] 21
9 SEG1 GRID3	20
10 SEG2 GRID2	] 19
11 SEG3 GRID1	] 18
12 SEG4 VDD	] 17
13 SEG5 SEG8	] 16
14 SEG6 SEG7	] 15

Pin Description And Structure Schematic

Pin	Name	Symbol	Description
1	Output(bits)	GRID12	Bits output, N tube
			Open drain output
2	Output(bits)	GRID13	Bits output, N tube
			Open drain output
3	Output(bits)	GRID14	Bits output, N tube

			Open drain output
4	Output(bits)	GRID15	Bits output, N tube
			Open drain output
5	Output(bits)	GRID16	Bits output, N tube
			Open drain output
6	Logically	VSS	Connect to GMD
7	Data input	DIN	Serial data input,
			input data changes
			at Low level of
			SCLK
			, transmitted at
			high level of SCLK
8	Clock input	SCLK	Enter data on the
			rising edge
9	Output	SEG1	Segment output, P
	(segment)		tube open drain
			output

r	1		
10	Output	SEG2	Segment output, P
	(segment)		tube open drain
			output
11	Output	SEG3	Segment output, P
	(segment)		tube open drain
			output
12	Output	SEG4	Segment output, P
	(segment)		tube open drain
			output
13	Output	SEG5	Segment output, P
	(segment)		tube open drain
			output
14	Output	SEG6	Segment output, P
	(segment)		tube open drain
			output
15	Output	SEG7	Segment output, P
	(segment)		tube open drain
			output

16	Output (segment)	SEG8	Segment output, P tube open drain output
17	Logic power supply	VDD	5V±10%
18	Output(bits)	GRID1	Bits output, N tube Open drain output
19	Output(bits)	GRID2	Bits output, N tube Open drain output
20	Output(bits)	GRID3	Bits output, N tube Open drain output
21	Output(bits)	GRID4	Bits output, N tube Open drain output
22	Output(bits)	GRID5	Bits output, N tube Open drain output

23	Output(bits)	GRID6	Bits output, N tube Open drain output
24	Output(bits)	GRID7	Bits output, N tube Open drain output
25	Output(bits)	GRID8	Bits output, N tube Open drain output
26	Output(bits)	GRID9	Bits output, N tube Open drain output
27	Output(bits)	GRID10	Bits output, N tube Open drain output
28	Output(bits)	GRID11	Bits output, N tube Open drain output

# 3. Electrical Property

Limit parameters	(Tamb=25°C,	Vss = 0V	unless oth	erwise specified)
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Parameter	Symbol	Condition	Rated value	Unit
Name				
Power supply	VCC		-0.5 ~ +7.0	V
voltage				
Logic input	VI1		-0.5~VDD+0.5	V
voltage				
LED Seg Drive	101		-50	mA
Output Current				
LED Grid drive	102		+200	mA
output current				
Power loss	PD		400	mW
Working	Topt		-40~+85	°C
temperature				
Storage	Tstg		-65~+150	°C
temperature				
Welding	TL	10s	250	°C
temperature				

Recommended Conditions (Ta =  $-40 \sim +85^{\circ}$ C, Vss = 0V)

Parameter	Symbol	Minimum	Typical	Maximum	Unit
name					
Logic supply	VDD		5		V
voltage					
High level	VIH	0.7VDD	-	VDD	V
input voltage					
	VIL	0	-	0.3VDD	V
Low level					
input voltage					

**Electrical Characteristics** 

Electrical Characteristics (Ta=-40~+85°C, VDD = 4.5V~5.5 V, GND=0V)

Parameter name	Symbol	Test Condition	Minimum	Typical	Maximum	Unit
High level output current	loh1	GRID1~GRID1 6, Vo = vdd-2V	-20	-25	-40	mA
	loh2	GRID1~GRID1 6, Vo = vdd-3V	-20	-30	-50	mA
Low level output current	IOL1	SEG1~SEG8 Vo=0.3V	80	140	-	mA
Low level output current	Idout	VO = 0.4V, dout	4	-	-	mA
High level output current tolerance	Itolsg	VO = VDD – 3V, GRID1~ GRID16 -	-	-	5	%
Input Current	II	VI = VDD / VSS	-	_	±1	μA

High level	VIH	CLK, DIN	0.7VDD	-		V
input						
voltage						
	VIL	CLK, DIN	-	-	0.3VDD	V
Low level						
input						
voltage						
Hysteretic	VH	CLK, DIN	-	0.35	-	V
voltage						
Dynamic	IDDdyn	No load,	-	-	5	MA
current		display off				
loss						

Switch Characteristics (unless otherwise specified, Tamb =  $-40 \sim +85^{\circ}$ C,

VDD= 4.5 ~ 5.5V)

Parameter	Symbol	Test	Minimum	Typical	Maximum	Unit
Name		Condition				
Oscillating	Fosc		-	450	-	KHz
frequency						

Transmission	tPLZ	$CLK \rightarrow$	-	-	300	ns
delay time		DIO CL =				
		15pF, RL				
		= 10Κ Ω				
	tPZL		-	-	100	
Rise Time	TTZH 1	GRID1 $\sim$	-	-	2	μs
		GRID16 CL				
		=300p F				
	TTZH 2	SEG1 $\sim$	-	-	0.5	μs
		SEG8 CL				
		=300p F				
Fall time	TTHZ	CL =	-	-	120	μs
		300pF,				
		Segn,				
		Gridn				
Maximum	Fmax	Duty Cycle	1	-	-	MHZ
clock		50%				
frequency						
Input	CI	-	-	-	15	pF
capacitance						

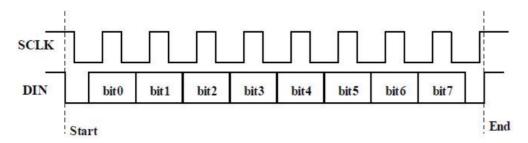
Clock Characteristics (Tamb=-40~+85°C, VDD=  $4.5 \sim 5.5$ V unless otherwise specified)

Parameter	Symbol	Test	Minimum	Typical	Maximum	Unit
Name		Condition				
Clock Pulse	PWCLK	-	400	-	-	ns
Width						
Strobe	PWSTB	-	1	-	-	μs
Width						
Data	tSETUP	-	100	-	-	ns
Building-up						
Time						
Data	tHOLD	-	100	-	-	ns
Retention						
Time						
Waiting	tWAIT	CLK↑→CLK↓	1	-	-	μs
Time						

# Interface Description

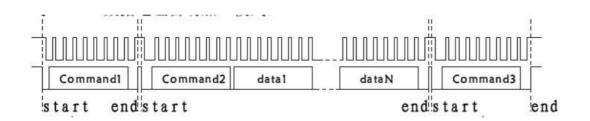
Microprocessor data communicates via the AIP1640 and two-wire bus interface. When CLK is high level and inputting data, the signal on DIN must be remained unchanged. Only when the clock signal on CLK is low level, the signal on DIN can be changed. The input of data is always low bit first and the high bit is transmitted later. The start condition of data input is when CLK is high level, DIN changes from low level to high level; the end condition is when CLK is high level, DIN changes from low level to high level.

The instruction data transmission process is as follows:



Instruction Data Transmission Format

Write SRAM data address automatically added 1 mode:



Automatic address write data format

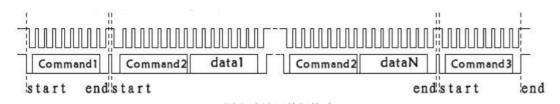
Command1: Setting data

Command2: Setting address

Data1~N: Transfer display data

Command3: Control display

#### Write SRAM data fixed address mode:



Fixed address write data format

## Command1: Setting data

#### Command2: Setting address

Data1~N: Transfer display data

Command3: Control display

#### Data instruction

Instructions are used to set the display mode and the status of the LED driver. The first byte entered by DIN is used as an instruction after the instruction START is valid. After decoding, the B7 and B6 bits are taken to distinguish different instructions.

<b>B7</b>	B6	Introduction
0	1	Data command setting Display control command setting
1	0	Display control command setting
1	1	Address command setting

If END is valid when an instruction or data transfers, the serial communication is initialized and the instruction or data being transferred is invalid (the previous transmitted instruction or data remains valid).

Data command settings:

B7	B6	B5	B4	B3	B2	B1	B0	Description	
0	1	Irrolo	vont		0			Address	
0	1	Irrele	vant		1	Irrele	vant	automatically added	
0	1	item,	fill	0		item,	fill in	Fixed address	
0	1	1 in 0		1		0		Universal mode	
0	0 1			1		5		Test mode	

Address command setting

<b>B</b> 7	<b>B</b> 6	B5	B4	B3	B2	B1	B0	Display address		
1	1	1		0	0	0	0	00H		
1	1	Irrele	evant	0	0	0	1	01H		
1	1	item.	fill in	0	0	1	0	02H		
1	1	,		0	0	1	1	03H		
1	1	0		0	1	0	0	04H		
1	1			0	1	0	1	05H		
1	1				1	1	0	06H		
1	1			0	1	1	1	07H		
1	1			1	0	0	0	08H		
1	1			1	0	0	1	09H		
1	1			1	0	1	0	0AH		
1	1					1	0	1	1	0BH
1	1				1	1	0	0	0CH	
1	1				1	0	1	0DH		
1	1				1	1	0	0EH		
1	1			1	1	1	1	OFH		

Display address command settings

At power-on, the address is set to 00H by default.

The correspondent relationship between display data and chip pins and

display addresses is shown in the following table:

SEG8	SEG7	SEG6	SEG5	SEG4	SEG3	SEG2	SEG1	
B7	B6	B5	B4	B3	<b>B</b> 2	B1	B0	
		Di	splay ad	dress 00	ЭН			GRID1
		Di	splay ad	dress 01	н			GRID2
		Di	splay ad	dress 02	2H			GRID3
		Di	splay ad	dress 03	BH			GRID4
		Di	splay ad	dress 04	ιH			GRID5
		Di	splay ad	dress 05	БH			GRID6
		Di	splay ad	dress 06	ын			GRID7
		Di	splay ad	dress 07	7H			GRID8
		Display address 08H GRID9				GRID9		
	Display address 09H GRID10				GRID10			
		Di	splay ad	dress 0/	<b>Η</b>			GRID11
		Dis	splay ad	dress OE	BH			GRID12
		Dis	splay ad	dress 00	ЭН			GRID13
		GRID14						
		GRID15						
		Di	splay ad	dress Ol	Ή			GRID16

The correspondent relationship between display data, address, and chip

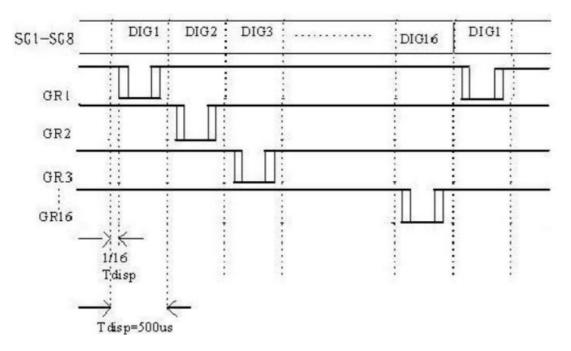
pins

Display control

MSB							LSE	3	
B7	B6	<b>B</b> 5	B4	B3	<b>B</b> 2	B1	B0	Fuction	Description
1	0			1	0	0	0		Set pulse width 1/16
1	- ×	Irre	lev	1	-		0		Set pulse width 2/16
1	0			1	0	0	1		Set pulse width 4/16
1	0			1	0	1	0	Prightnoss	Set pulse width 10/16
1	0	ant		1	0	1	1	Brightness	
1	0			1	1	0	0	setting	Set pulse width 11/16
1	0	iter	n,	1	1	0	1		Set pulse width 12/16
1	0		•	1	1	1	0		Set pulse width 13/16
1	0	fill i	n 0	1	1	1	1	Display switch	Set pulse width 14/16
1	0			0	Х	Х	Х	setting	Display on
1	0			1	Х	Х	X		Display off

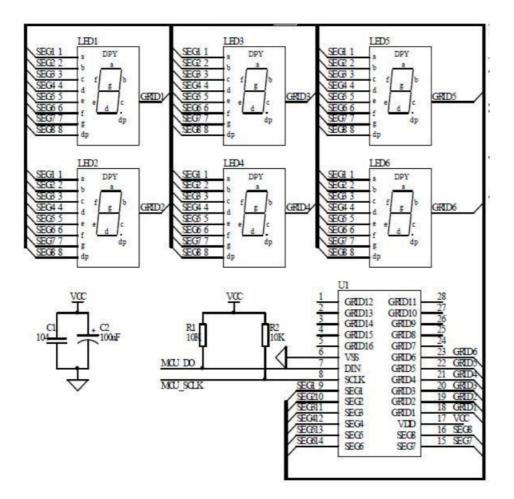
Display mode control instruction

## Display cycle



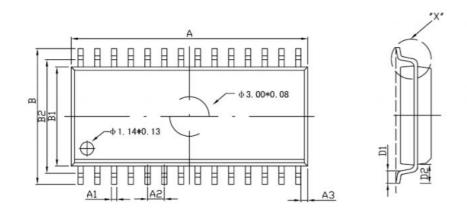
Typical application diagram and instructions

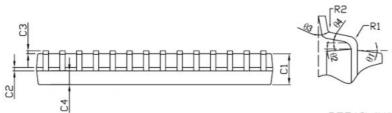
The digital tube connected in the circuit diagram is a common cathode digital tube:



Package size and outline drawing

SOP28 outline drawing and package size





DETAIL"X"

Label	Minimum	Maximum	Label	Minimum	Maximum		
A	17.83	18.03	C4	1.0	043TYP		
A1	0,406	4TYP	D1	0.70	0,90		
A2	1.27	TYP	D2	1.3	1.395TYP		
A3	0,51	TYP	R1	0.	0.508TYP		
В	9.90	10.50	R2	0,5	508TYP		
B1	7,42	7,62	θ1	7°	TYP		
B2	8.9	TYP	θ2	5°	TYP		
C1	2.24 2.44		θ3	4°	TYP		
C2	0.204	0.33	θ4	10	° TYP		
C3	0.10	0.25			,		

**Declarations and Precautions:** 

The name and content of toxic and hazardous substances or elements in

the product

Component	Toxic o	Toxic or harmful substances or elements								
	Lead (Pb)	Mercu ry (Hg)	Cadmium (Cd)	sixth-order chromium (Cr(VI))		Polybrominated biphenyl (PBBs)	Polybro minate d biphe nyl Ethers ( PBDEs)			
Lead Frame	0	0	0	0	0		0			
Sealing Gum	0	0	0	0	0		0			
Chip	0	0	0	0	0		0			
Inner Lead	0	0	0	0	0		0			
Loading Glue	0	0	0	0	0		0			
Description	elei	o o o o   o: indicates that the content of the toxic or hazardous substance or element is less than the SJ/T11363-2006 standard detection limit. x: indicates that the content of the toxic or hazardous substance or element exceeds the limit of SJ/T11363-2006 standard requirements.								

## Attention

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